



## Material Content Data Sheet



<b>Sales Product Name</b>		IPB100N12S3-05		<b>Issued</b>		4. July 2019		
<b>MA#</b>		MA003664472						
<b>Package</b>		PG-TO263-3-2		<b>Weight*</b>		1566.56 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	15.369	0.98	0.98	9811	9811
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		58	
	non noble metal	iron	7439-89-6	0.304	0.02		194	
	non noble metal	copper	7440-50-8	304.026	19.41	19.44	194072	194324
	non noble metal	aluminium	7429-90-5	9.780	0.62	0.62	6243	6243
wire	non noble metal	aluminium	7429-90-5	9.780	0.62	0.62	6243	6243
encapsulation	organic material	carbon black	1333-86-4	10.040	0.64		6409	
	plastics	epoxy resin	-	110.439	7.05		70498	
	inorganic material	silicondioxide	60676-86-0	548.849	35.03	42.72	350352	427259
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6164	6164
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	146	147
solder	non noble metal	tin	7440-31-5	0.188	0.01		120	
	noble metal	silver	7440-22-4	0.235	0.02		150	
	non noble metal	lead	7439-92-1	8.975	0.57	0.60	5729	5999
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		105	
	non noble metal	iron	7439-89-6	0.548	0.04		350	
	non noble metal	copper	7440-50-8	547.666	34.96	35.01	349598	350053
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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